

## 1. General description

Ultrafast power diode in a 2-lead TO247-2L plastic package.

## 2. Features and benefits

- Fast switching
- Very low on-state loss
- Low leakage current
- Low thermal resistance

## 3. Applications

- Active PFC in air conditioner
- S.M.P.S Power Factor Correction (PFC)
- Half-bridge / full-bridge switched-mode power supplies

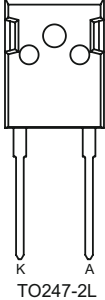
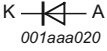
## 4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Values			Unit
<b>Absolute maximum rating</b>						
$V_{RRM}$	repetitive peak reverse voltage		600			V
$I_{F(AV)}$	average forward current	$\delta = 0.5$ ; square-wave pulse; $T_{mb} \leq 129$ °C; <a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a>	30			A
$I_{FRM}$	repetitive peak forward current	$\delta = 0.5$ ; $t_p = 25$ $\mu$ s; $T_{mb} \leq 129$ °C; square-wave pulse	60			A
$I_{FSM}$	non-repetitive peak forward current	$t_p = 10$ ms; $T_{j(init)} = 25$ °C; sine-wave pulse; <a href="#">Fig. 4</a>	290			A
		$t_p = 8.3$ ms; $T_{j(init)} = 25$ °C; sine-wave pulse	330			A
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static characteristics</b>						
$V_F$	forward voltage	$I_F = 30$ A; $T_j = 25$ °C; <a href="#">Fig. 6</a>	-	1.18	1.55	V
		$I_F = 30$ A; $T_j = 150$ °C; <a href="#">Fig. 6</a>	-	0.98	-	V
<b>Dynamic characteristics</b>						
$t_{rr}$	reverse recovery time	$I_F = 1$ A; $V_R = 30$ V; $dI_F/dt = 50$ A/ $\mu$ s; $T_j = 25$ °C; <a href="#">Fig. 7</a>	-	42	75	ns
		$I_F = 30$ A; $V_R = 400$ V; $dI_F/dt = 200$ A/ $\mu$ s; $T_j = 25$ °C; <a href="#">Fig. 7</a>	-	65	-	ns
		$I_F = 30$ A; $V_R = 400$ V; $dI_F/dt = 200$ A/ $\mu$ s; $T_j = 125$ °C; <a href="#">Fig. 7</a>	-	101	-	ns

## 5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode		
2	A	anode		
mb	mb	mounting base; connected to cathod		

## 6. Ordering information

Table 3. Ordering information

Type number	Package name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
BYV30W-600PT2	TO247-2L	BYV30W-600PT2Q	Tube	30	TO247L-2L	10-Nov-2020

## 7. Marking

Table 4. Marking codes

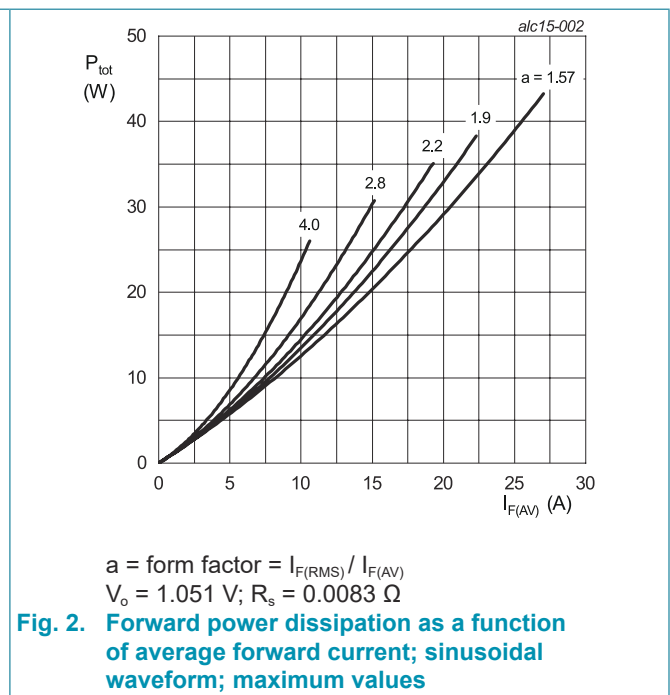
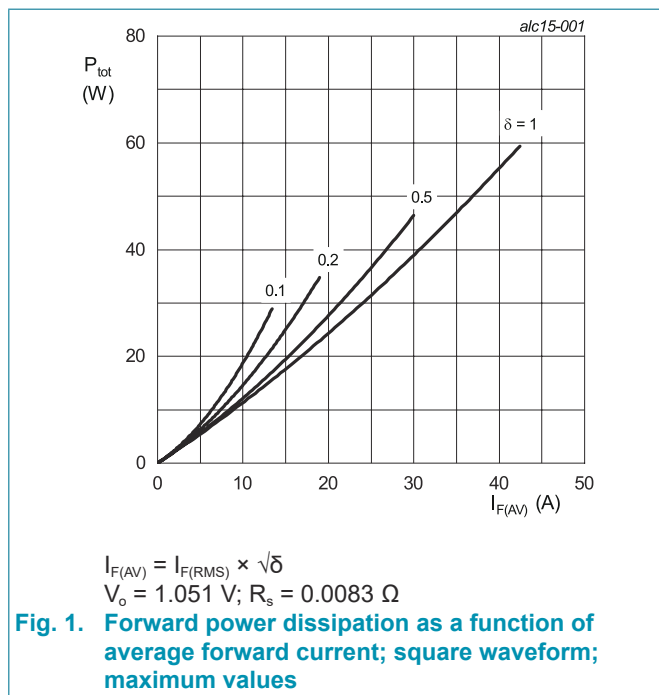
Type number	Marking codes
BYV30W-600PT2	BYV30W 600PT2

## 8. Limiting values

**Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Values	Unit
$V_{RRM}$	repetitive peak reverse voltage		600	V
$V_{RWM}$	crest working reverse voltage		600	V
$V_R$	reverse voltage	DC	600	V
$I_{F(AV)}$	average forward current	$\delta = 0.5$ ; square-wave pulse; $T_{mb} \leq 129\text{ }^\circ\text{C}$ ; <a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a>	30	A
$I_{FRM}$	repetitive peak forward current	$\delta = 0.5$ ; $t_p = 25\text{ }\mu\text{s}$ ; $T_{mb} \leq 129\text{ }^\circ\text{C}$ ; square-wave pulse	60	A
$I_{FSM}$	non-repetitive peak forward current	$t_p = 10\text{ ms}$ ; $T_{j(\text{init})} = 25\text{ }^\circ\text{C}$ ; sine-wave pulse; <a href="#">Fig. 4</a>	290	A
		$t_p = 8.3\text{ ms}$ ; $T_{j(\text{init})} = 25\text{ }^\circ\text{C}$ ; sine-wave pulse	330	A
$T_{stg}$	storage temperature		-55 to 175	$^\circ\text{C}$
$T_j$	junction temperature		175	$^\circ\text{C}$



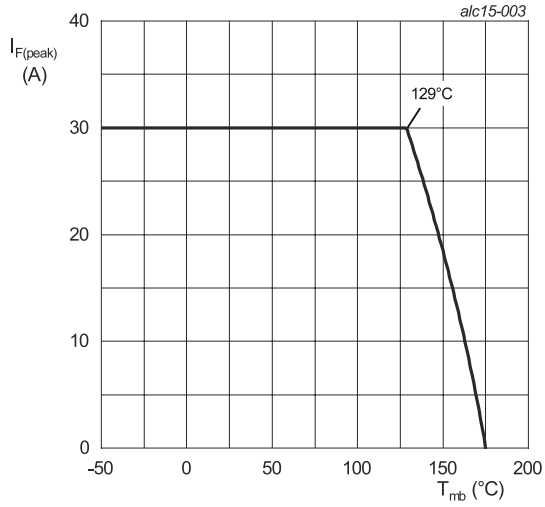


Fig. 3. Forward current as a function of mounting base temperature; maximum values

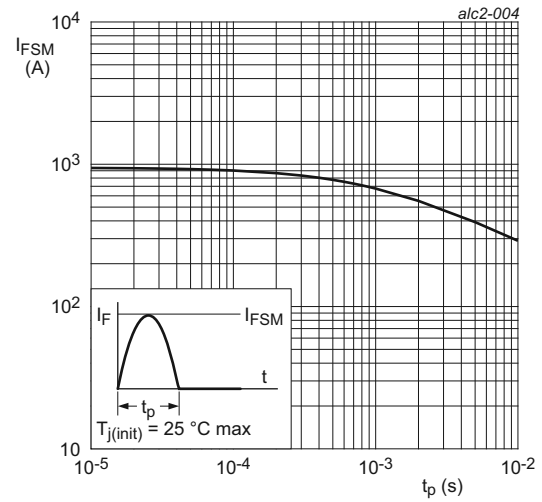


Fig. 4. Non-repetitive peak forward current as a function of pulse width; sinusoidal waveform; maximum values

### 9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	<a href="#">Fig. 5</a>	-	-	1	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient free air	in free air	-	45	-	K/W

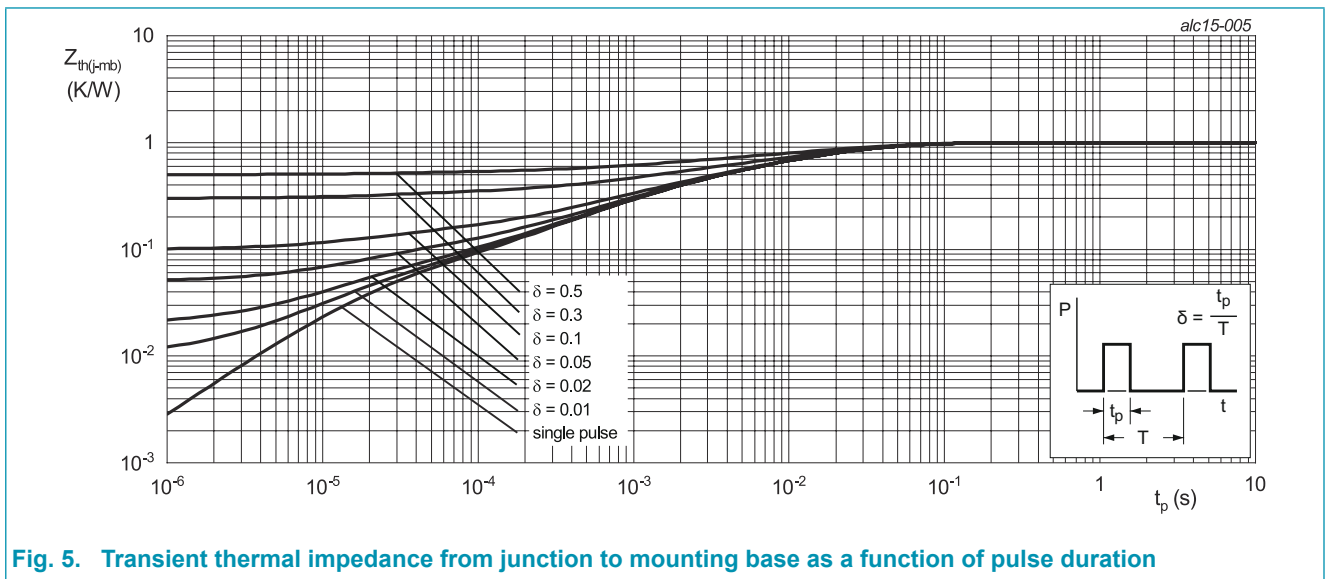
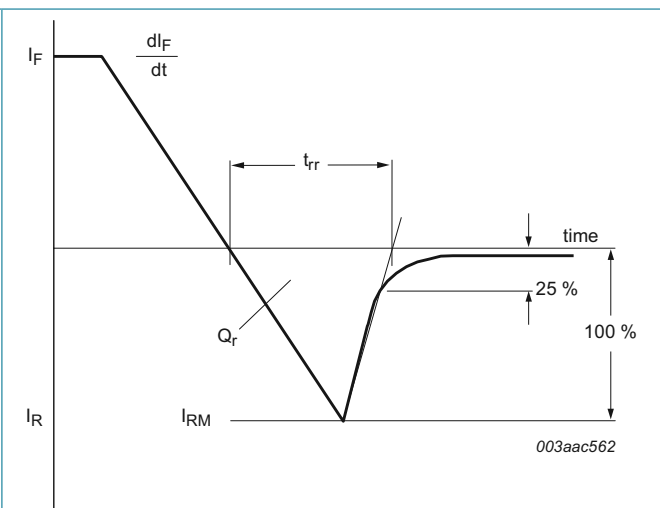
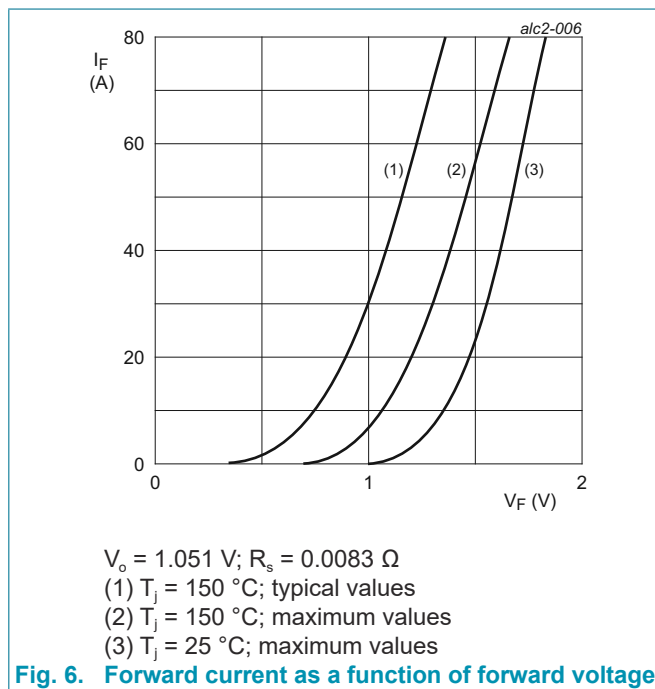


Fig. 5. Transient thermal impedance from junction to mounting base as a function of pulse duration

### 10. Characteristics

Table 7. Characteristics

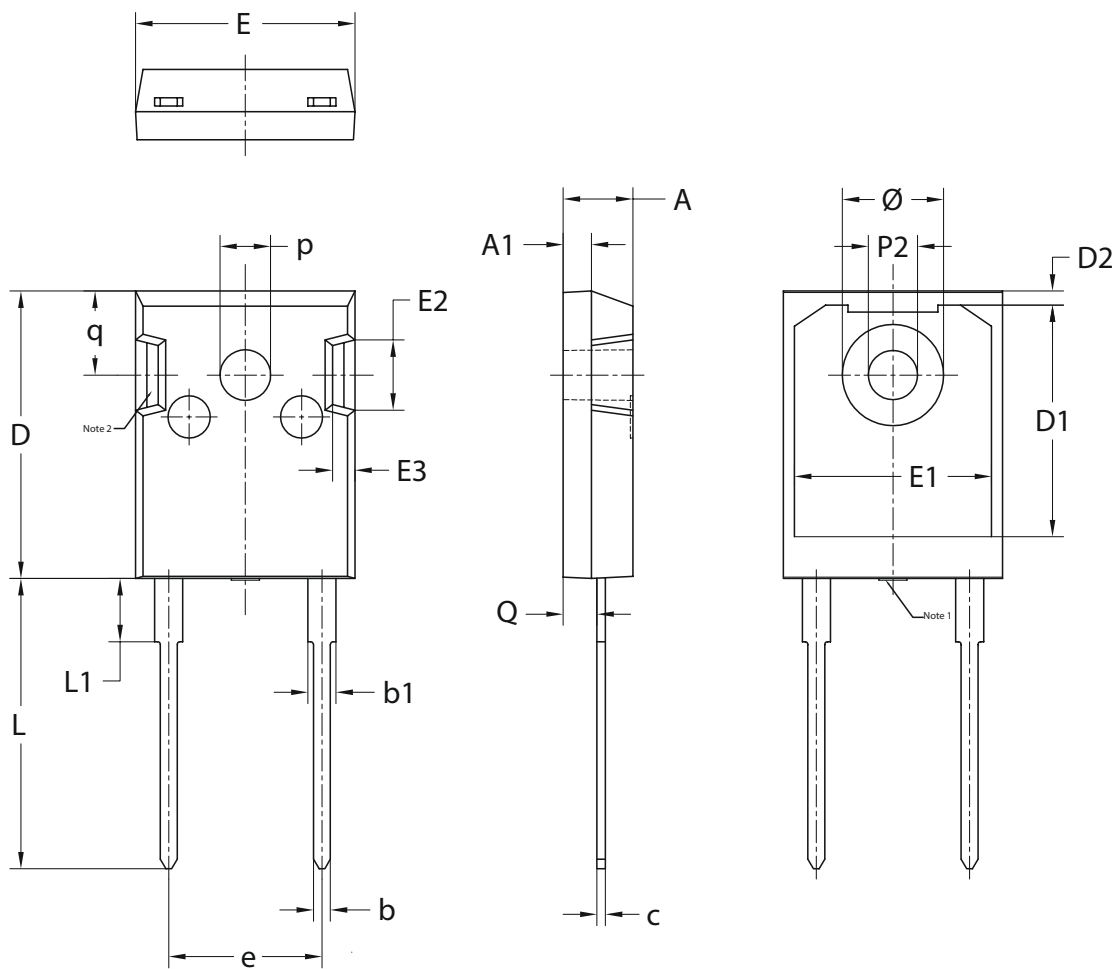
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static characteristics</b>						
$V_F$	forward current	$I_F = 30\text{ A}; T_j = 25\text{ °C}; \text{Fig. 6}$	-	1.18	1.55	V
		$I_F = 30\text{ A}; T_j = 150\text{ °C}; \text{Fig. 6}$	-	0.98	-	V
$I_R$	reverse current	$V_R = 600\text{ V}; T_j = 25\text{ °C}$	-	2	10	$\mu\text{A}$
		$V_R = 600\text{ V}; T_j = 125\text{ °C}$	-	-	500	$\mu\text{A}$
<b>Dynamic characteristics</b>						
$Q_r$	reverse charge	$I_F = 30\text{ A}; V_R = 400\text{ V}; dI_F/dt = 200\text{ A}/\mu\text{s}; T_j = 25\text{ °C}; \text{Fig. 7}$	-	272	-	nC
		$I_F = 30\text{ A}; V_R = 400\text{ V}; dI_F/dt = 200\text{ A}/\mu\text{s}; T_j = 125\text{ °C}; \text{Fig. 7}$	-	775	-	nC
$t_{rr}$	reverse recovery time	$I_F = 1\text{ A}; V_R = 30\text{ V}; dI_F/dt = 50\text{ A}/\mu\text{s}; T_j = 25\text{ °C}; \text{Fig. 7}$	-	42	75	ns
		$I_F = 30\text{ A}; V_R = 400\text{ V}; dI_F/dt = 200\text{ A}/\mu\text{s}; T_j = 25\text{ °C}; \text{Fig. 7}$	-	65	-	ns
		$I_F = 30\text{ A}; V_R = 400\text{ V}; dI_F/dt = 200\text{ A}/\mu\text{s}; T_j = 125\text{ °C}; \text{Fig. 7}$	-	101	-	ns
$I_{RM}$	peak reverse recovery current	$I_F = 30\text{ A}; V_R = 400\text{ V}; dI_F/dt = 200\text{ A}/\mu\text{s}; T_j = 25\text{ °C}; \text{Fig. 7}$	-	8.4	-	A
		$I_F = 30\text{ A}; V_R = 400\text{ V}; dI_F/dt = 200\text{ A}/\mu\text{s}; T_j = 125\text{ °C}; \text{Fig. 7}$	-	15.2	-	A



### 11. Package outline

Plastic single-ended through-hole package; heatsink mounted; 1 mounting hole; 2 leads TO-247

TO247-2L



UNIT	A	A <sub>1</sub>	b	b <sub>1</sub>	c	D	D <sub>1</sub> ⊕	D <sub>2</sub>	E	E <sub>1</sub>	E <sub>2</sub>	E <sub>3</sub>	e	L	L <sub>1</sub>	P <sub>2</sub>	p	Q	q	Ø
mm	5.20	2.10	1.40	2.20	0.70	20.60	16.20	1.20	15.75	14.22	5.20	1.80	10.90	20.72	4.75	3.60	3.70	2.60	6.18	7.30
	4.70	1.90	1.00	1.80	0.50	20.30	16.87	0.80	15.45	13.82	4.80	1.40	BSC	20.22	4.25	3.40	3.50	2.20	5.78	7.10

Note:

1. Mold resin protrusion max 0.127mm.
2. Metal exposed with Sn plating.

## 12. Legal information

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Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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